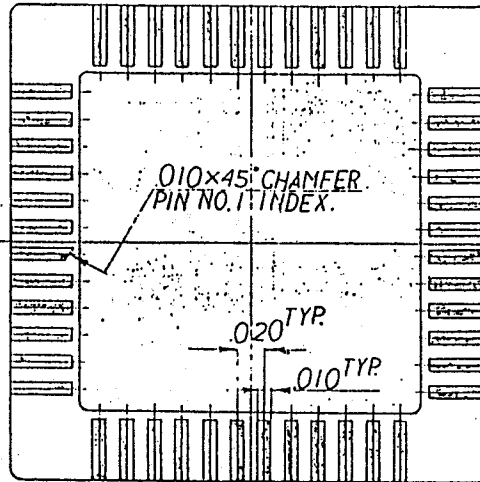


- NOTES
- 1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
  - 2. LEAD RESISTANCE: 07  $\Omega$  MAX.
  - 3. DIE ATTACH AREA TO BE METALLIZED
  - 4. SEAL AREA TO BE METALLIZED
  - 5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

MODIFICATIONS	△ ADDED: VENDOR'S OPTION, CHANGED: NOTE 1 JUL 18 83 J. Nando / J. Antonick	NAME <b>48 LEAD SIDE BRAZE PACKAGE</b>	TOLERANCES: UNLESS OTHERWISE SPECIFIED ±1.0% N.L.T. ±.005	DRAWN <i>J. Antonick</i>	CHECKED <i>J. Antonick</i>
	△ ADDED: NOTES, VENDOR'S OPTION AT TIE-BAR, SEP 10 '83 K. Dryden / J. Antonick	SCALE 4 : 1	MATERIAL AS INDICATED	APPROVED <i>J. Antonick</i>	DATE APR 28 '80
	△ CHANGED: .590 → .595 LEAD FLAM. .040 → .050 CHANGE	DATE FEB 13 82	DRAWN <i>K. Dryden</i>	CHECKED <i>J. Antonick</i>	APPROVED <i>J. Antonick</i>
	KYOTO CERAMIC CO., LTD.	KYOTO JAPAN	DWG. NO. KD-80177--C	1/3	



BONDING PATTERN

MODIFICATIONS						TOLERANCES: UNLESS OTHERWISE SPECIFIED _____	DRAWN	CHECKED
							<i>M. Fukuda</i> APPROVED	<i>M. Fukuda</i> DATE
								APR. 28. '80
CHANGE	DATE	DRAWN	CHECKED	APPROVED	NAME <b>48 LEAD SIDE BRAZE PACKAGE</b> SCALE 10 : 1 MATERIAL _____	KYOTO CERAMIC CO., LTD. KYOTO JAPAN	DWG. NO. KP-80177-C	2/3